



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251218004.1
Qualification of TI Clark as an additional Assembly site for select devices
Change Notification / Sample Request

Date: December 19, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251218004.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
UCC27201DRMR	UCC27201DRMR
UCC27211ADRMR	UCC27211ADRMR

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251218004.1		PCN Date:	December 19, 2025	
Title:	Qualification of TI Clark as an additional Assembly site for select devices				
Customer Contact:	Change Management team	Dept:	Quality Services		
Proposed 1st Ship Date:	March 19, 2026	Sample requests accepted until:	February 17, 2026*		
*Sample requests received after February 17, 2026 will not be supported.					
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Material
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of TI Clark as an additional Assembly site for select devices. No material differences between sites.					
		Current		Additional	
	Assembly site	CDAT		CLARK	
Qual details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Impact on Environmental Ratings					
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.					
	RoHS	REACH	Green Status	IEC 62474	
	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	
Changes to product identification resulting from this PCN:					
Assembly Site Information:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
TI Chengdu	CDA	CHN	Chengdu		
TI Clark	QAB	PHL	Pampanga		
Sample Product Shipping Label (not actual product label)					

 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL 2 / 260C / 1 YEAR SEAL DT MSL 1 / 235C / UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750	 	(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS
Product Affected:		
UCC27200DRMR	UCC27201DRMR	UCC27211ADRMR

Qualification Report

Approve Date 18-December-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: UCC27200DRMR	Qual Device: UCC27201DRMR	Qual Device: UCC27211ADRMR	QBS Reference: SN65HVD01DRCR	QBS Reference: UCC27301AODDARQ1	QBS Reference: LM5157QRTERQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	3/231/0	3/231/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	1/77/0	1/77/0	1/77/0	3/231/0	3/231/0	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	1/77/0	1/77/0	3/231/0	3/231/0	3/231/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	3/135/0	-
HTOL	B1	Life Test	150C	300 Hours	-	-	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	150C	24 Hours	-	-	-	-	3/2400/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	1/15/0	1/15/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	1/22/0	-	-	-	-	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	3/30/0	3/30/0
ESD	E2	ESD CDM	-	500 Volts	-	-	-	-	1/3/0	-
ESD	E2	ESD HBM	-	2000 Volts	-	-	-	-	1/3/0	-
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/6/0	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	-
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-	-	3/90/0	-
FTY	E6	Final Test Yield	-	-	-	-	-	-	1/1/0	-

QBS: Qual By Similarity, also known as Generic Data

Qual Device UCC27200DRMR is qualified at MSL1 260C

Qual Device UCC27201DRMR is qualified at MSL1 260C

Qual Device UCC27211ADRMR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2310-041

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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